

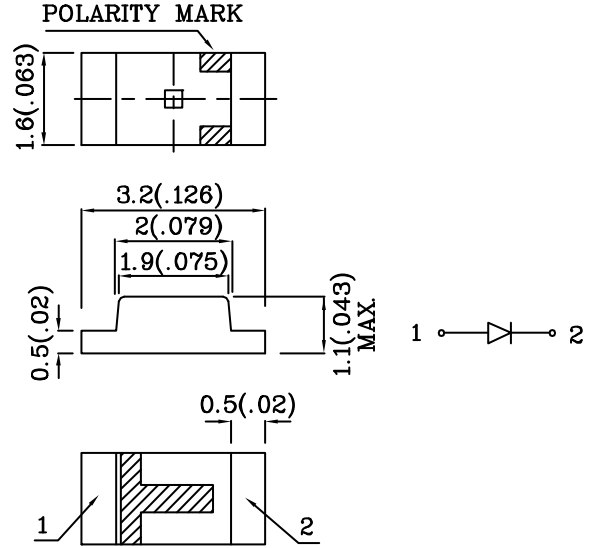
Features

- 3.2mmx1.6mm SMT LED, 1.1mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.



Notes:

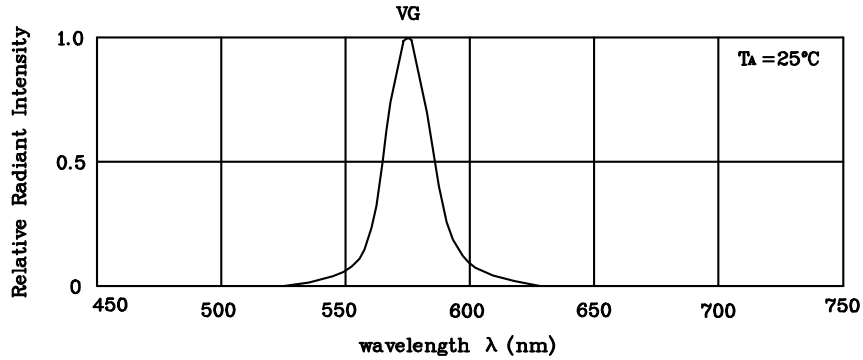
1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008)$ " unless otherwise noted.
3. Specifications are subject to change without notice.



Absolute Maximum Ratings (TA=25°C)		VG (InGaAlP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	150	mA
Power Dissipation	PT	75	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	

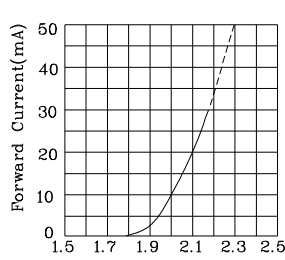
Operating Characteristics (TA=25°C)		VG (InGaAlP)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	2.1	V
Forward Voltage (Max.) (IF=20mA)	VF	2.5	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λP	574	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λD	570	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	$\Delta\lambda$	20	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λP	Viewing Angle 2 θ 1/2
				min.	typ.		
XZVG55W	Green	InGaAlP	Water Clear	10	39	574	120°

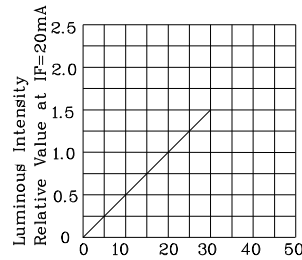


RELATIVE INTENSITY Vs. WAVELENGTH

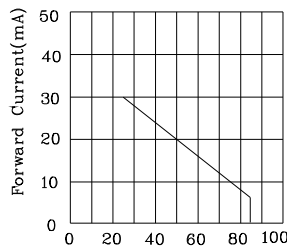
❖ VG



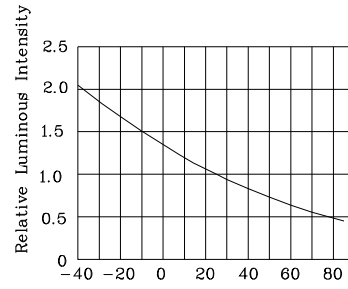
Forward Voltage(V)
FORWARD CURRENT Vs. FORWARD VOLTAGE



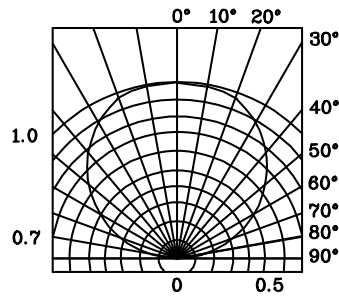
I_F -Forward Current (mA)
LUMINOUS INTENSITY Vs. FORWARD CURRENT



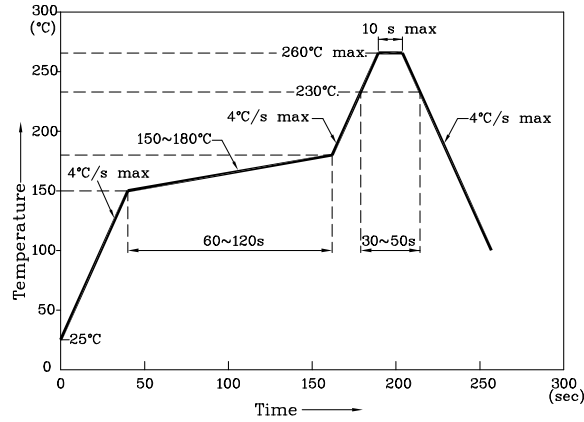
Ambient Temperature T_A ($^\circ\text{C}$)
FORWARD CURRENT DERATING CURVE



Ambient Temperature T_A ($^\circ\text{C}$)
LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE



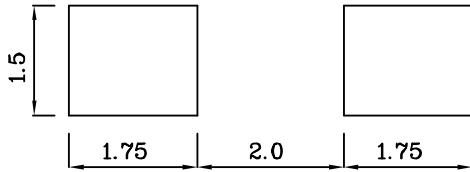
Reflow Soldering Profile For Lead-free SMT Process.



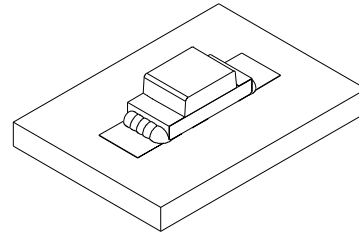
NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

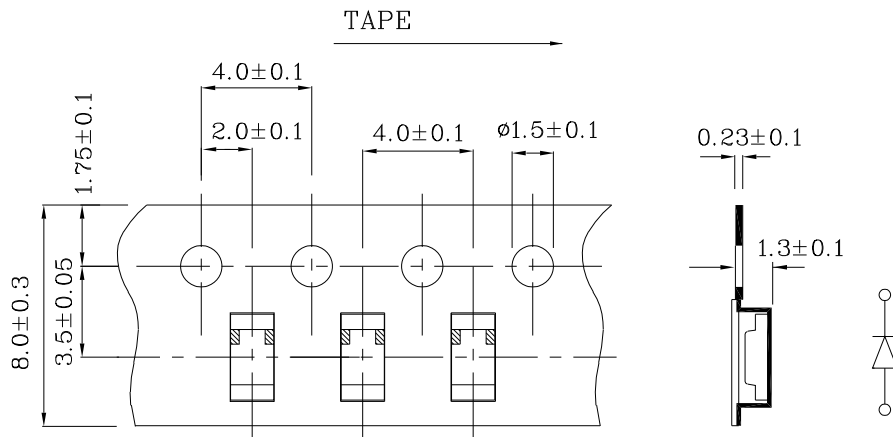
❖ Recommended Soldering Pattern
(Units : mm; Tolerance: ± 0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

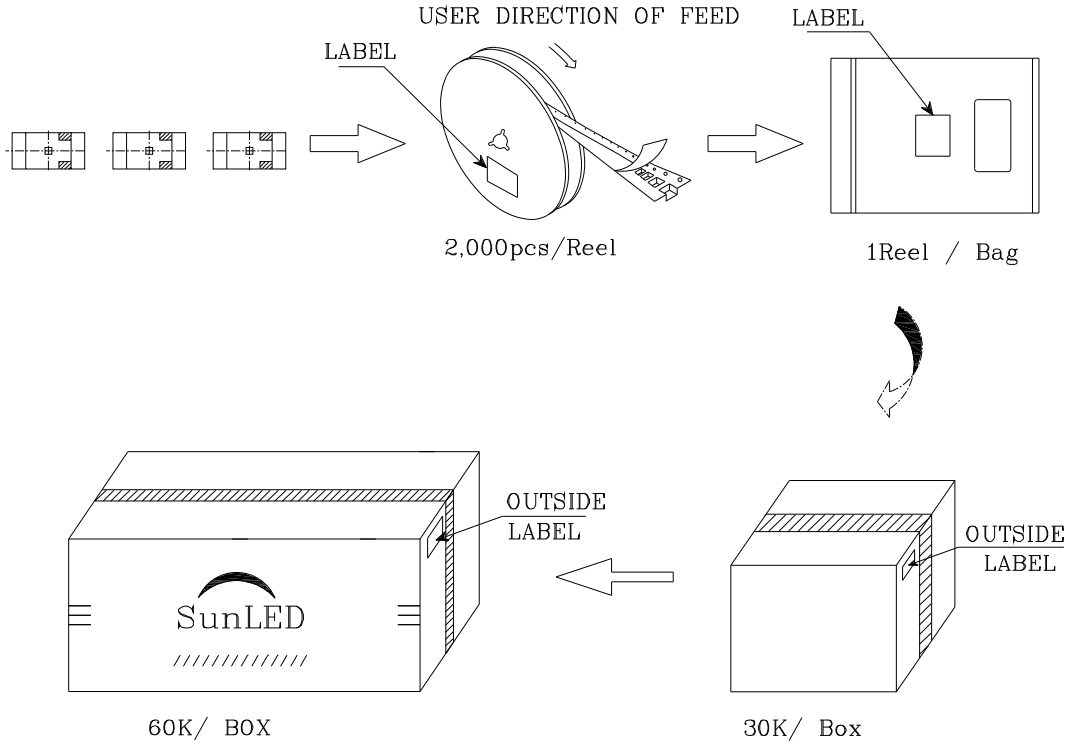

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

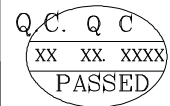

1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

XZVG55W

	
P/NO : XZxxx55x	
QTY : 2,000 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	